P-Channel 20 V (D-S) MOSFET

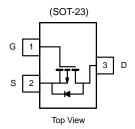
PRODUCT SUMMARY				
V _{DS} (V)	- 20			
$R_{DS(on)}(\Omega)$ at $V_{GS} = -4.5 \text{ V}$	0.113			
$R_{DS(on)}(\Omega)$ at $V_{GS} = -2.5 \text{ V}$	0.159			
I _D (A)	- 2.8			
Configuration	Single			

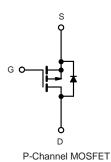
FEATURES

- DT-Trench Power MOSFET
- AEC-Q101 Qualified^d
- 100 % R_q and UIS Tested
- Compliant to RoHS Directive 2002/95/EC









ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V_{DS}	- 20	V		
Gate-Source Voltage		V_{GS}	± 8	V		
Continuous Drain Current	T _C = 25 °C	1	- 2.8			
	T _C = 125 °C	I _D	- 2.1			
Continuous Source Current (Diode Conduction)a	ntinuous Source Current (Diode Conduction) ^a		- 2	Α		
Pulsed Drain Current ^b	d Drain Current ^b		- 10			
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	- 5			
Single Pulse Avalanche Energy		E _{AS}	4	mJ		
Maximum Power Dissipation ^b	T _C = 25 °C		3	W		
	T _C = 125 °C	P_D	1	VV		
Operating Junction and Storage Temperature Range	•	T _J , T _{stg}	- 55 to + 175	°C		

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount ^c	R_{thJA}	166	°C/W	
Junction-to-Foot (Drain)		R _{thJF}	50	C/VV	

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.

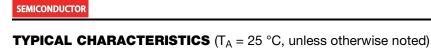


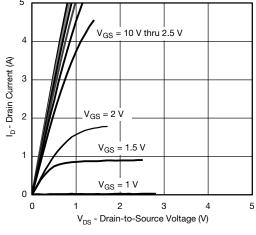
SPECIFICATIONS (T _C = 25 °C, unless otherwise noted) PARAMETER SYMBOL TEST CONDITIONS MIN. TYP. MAX. UNIT								
PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT		
Static					1	T		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0$, $I_D = -250 \mu\text{A}$		- 20	-	-	V	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$		- 0.45	-	- 1.5		
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$		-	-	± 100	nA	
		$V_{GS} = 0 V$	V _{DS} = - 20 V	-	-	- 1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	V _{DS} = - 20 V, T _J = 125 °C	1	-	- 50	μΑ	
		$V_{GS} = 0 V$	V _{DS} = - 20 V, T _J = 175 °C	-	-	- 150		
On-State Drain Current ^a	I _{D(on)}	V _{GS} = - 4.5 V	$V_{DS} \ge 5 V$	- 3	-	-	Α	
Datis Os as Os Olds Beststand	Ь	V _{GS} = - 4.5 V	I _D = - 1.8 A	-	0.113	0.125	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 2.5 V	I _D = - 1 A	-	0.159	0.175		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 1.6 V, I _D = - 1.8 A		-	7	-	S	
Dynamic ^b								
Input Capacitance	C _{iss}		V _{GS} = 0 V V _{DS} = - 10 V, f = 1 MHz	-	320	375	pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$		-	80	100		
Reverse Transfer Capacitance	C _{rss}			-	55	70		
Total Gate Charge ^c	Qg			-	5	8		
Gate-Source Charge ^c	Q _{gs}	V _{GS} = - 4.5 V	4.5 V $V_{DS} = -10 \text{ V}, I_D = -1.8 \text{ A}$	-	0.7	-	nC	
Gate-Drain Charge ^c	Q _{gd}			-	1.3	-		
Gate Resistance	R _g		f = 1 MHz		10	14.5	Ω	
Turn-On Delay Time ^c	t _{d(on)}	V_{DD} = - 10 V, R_L = 10 Ω I_D \cong - 1 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		-	15	22		
Rise Time ^c	t _r			-	14	21	- ns	
Turn-Off Delay Time ^c	t _{d(off)}			-	30	45		
Fall Time ^c	t _f			-	9	15		
Source-Drain Diode Ratings and Characteristics ^b								
Pulsed Current ^a	I _{SM}			-	-	- 2.2	Α	
Forward Voltage	V _{SD}	I _F =	-	- 0.8	- 1.2	V		

Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

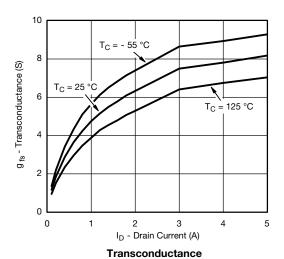
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

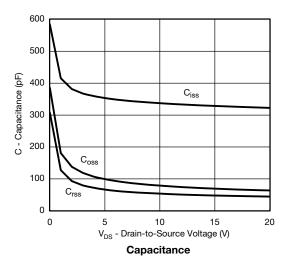


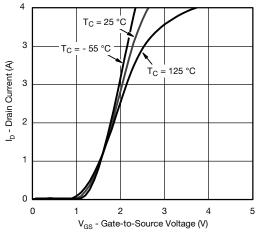


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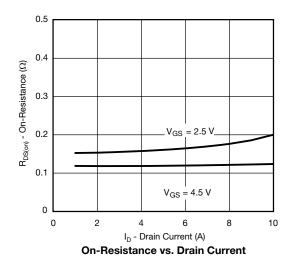
Output Characteristics







Transfer Characteristics



2

Q_g - Total Gate Charge (nC) **Gate Charge**

3

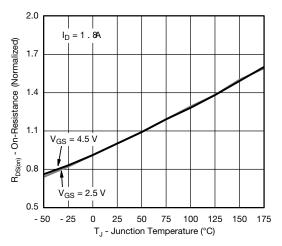
4

5

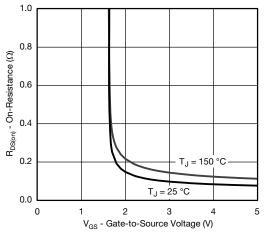
0



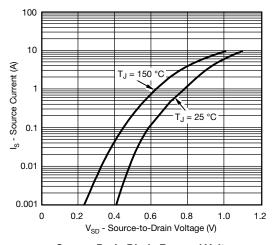
TYPICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)



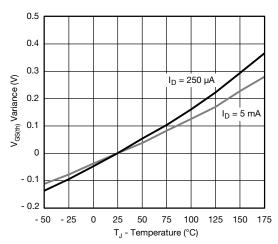
On-Resistance vs. Junction Temperature



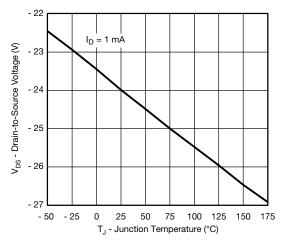
On-Resistance vs. Gate-to-Source Voltage



Source-Drain Diode Forward Voltage



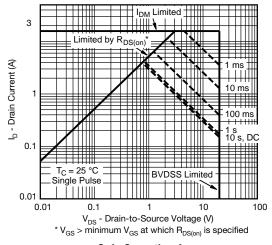
Threshold Voltage



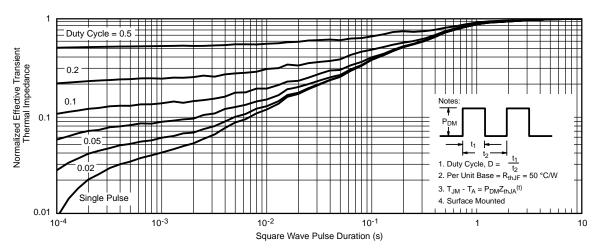
Drain Source Breakdown vs. Junction Temperature



THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



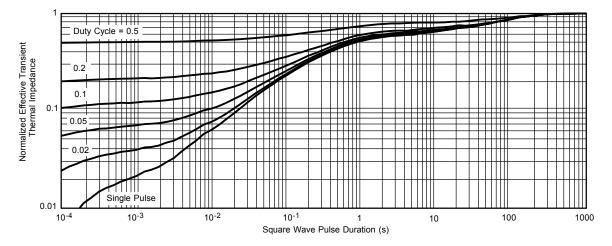
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Foot

THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)

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Normalized Thermal Transient Impedance, Junction-to-Ambient

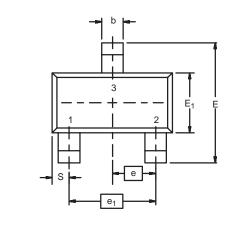
Note

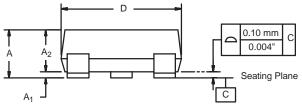
- The characteristics shown in the two graphs
- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction-to-Foot (25 °C)

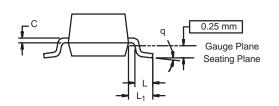
are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



SOT-23: 3-LEAD







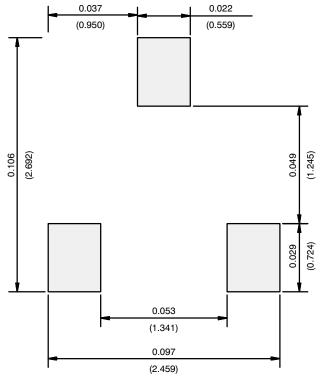
Min 0.89	Max	Min	NA		
0.89		******	Max		
	1.12	0.035	0.044		
0.01	0.10	0.0004	0.004		
0.88	1.02	0.0346	0.040		
0.35	0.50	0.014	0.020		
0.085	0.18	0.003	0.007		
2.80	3.04	0.110	0.120		
2.10	2.64	0.083	0.104		
1.20	1.40	0.047	0.055		
0.95 BSC		0.0374 Ref			
1.90	BSC	0.0748	Ref		
0.40	0.60	0.016	0.024		
0.64 Ref		0.025	Ref		
0.50 Ref		0.50 Ref		0.020	Ref
3°	8°	3°	8°		
	0.35 0.085 2.80 2.10 1.20 0.95 1.90 0.40 0.64 0.50	0.35 0.50 0.085 0.18 2.80 3.04 2.10 2.64 1.20 1.40 0.95 BSC 1.90 BSC 0.40 0.60 0.50 Ref	0.35 0.50 0.014 0.085 0.18 0.003 2.80 3.04 0.110 2.10 2.64 0.083 1.20 1.40 0.047 0.95 BSC 0.0374 1.90 BSC 0.0748 0.40 0.60 0.016 0.64 Ref 0.025 0.50 Ref 0.020 3° 8° 3°		

ECN: S-03946-Rev. K, 09-Jul-01

DWG: 5479



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)





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